





KEEP AREA

KEEP OUT AREA

/////// PAD AREA

PCB THROUGH HOLE

MATERIALS

HOUSING: HI-TEMP. PLASTIC (UL 94V-0)

SHELL: SUS, NICKLE PLATING SOLDER PAD: SUS, GOLD PLATING

TERMINAL: COPPER ALLOY, GOLD PLATED

SPECIFICATION

CURRENT RATING: 0.5 AMP MAX

DIELECTRIC WITHSTANDING: 500V AC FOR ONE MINUTE

CONTACT RESISTANCE: 100m OHMS MAX

INSULATION RESISTANCE: 1000M OHMS MIN AT DC 500V

OPERATION TEMPERATURE: -40°C~+85°C

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SIZE A4

PPOJECTION - -

照片框

MISCT-W1215X-06-LF SERIES	ORDER INFORMATION	
90°SMT HIGH 1.5mm	MISCT-W1215X-06-LF	
	90°SMT HIGH 1.5mm	

DESCRIPTION: MICRO SIM CARD, 6PIN, PCB MOUNT, SMT, METAL SHIELD, FEMALE, H=1.50mm